

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT6963949

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
<b>CONVEYING PARTY DATA</b>		
Name	Execution Date	
HELIANTHOS B.V.	05/07/2012	

<b>RECEIVING PARTY DATA</b>		
Name:	HYET ENERGY SYSTEMS B.V.	
Street Address:	LEEMANSWEG 15	
City:	6827 BX ARNHEM	
State/Country:	NETHERLANDS	

<b>PROPERTY NUMBERS Total: 1</b>		
Property Type	Number	
Patent Number:	8105868	

<b>CORRESPONDENCE DATA</b>		
Fax Number:		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	7038366400	
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Correspondent Name:	OLIFF PLC	
Address Line 1:	11 CANAL CENTER PLAZA, SUITE 200	
Address Line 4:	ALEXANDRIA, VIRGINIA 22314	

ATTORNEY DOCKET NUMBER:	141658
NAME OF SUBMITTER:	JOEL S. ARMSTRONG
SIGNATURE:	/JOEL S. ARMSTRONG/
DATE SIGNED:	10/12/2021

Total Attachments: 3
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## DEED OF ASSIGNMENT OF INTELLECTUAL PROPERTY RIGHTS

### THE UNDERSIGNED:

- (1) HELIANTHOS B.V. a company incorporated under the laws of the Netherlands, having its registered address at Westervoortsedijk 71 in (6827 AV) Arnhem, the Netherlands and registered with the Trade Register of the Dutch Chamber of Commerce under file number 09155926, duly represented by Mr. Peter Smink (the Assignor); and
- (2) HyET ENERGY SYSTEMS B.V. i.o., a company in the process of being incorporated under the laws of the Netherlands, intended to have its registered address at Leemansweg 15, 6827 BX Arnhem, The Netherlands and to be registered with the Trade Register of the Dutch Chamber of Commerce, duly represented by Mr. Rombout Adriaan Swanborn (the Assignee).

The Assignor and Assignee are hereinafter also referred to as the Parties and each as a Party.

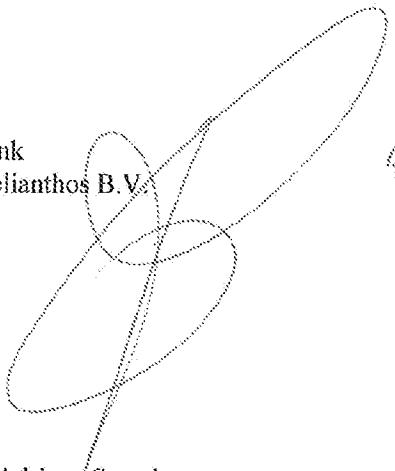
### HEREBY AGREE AS FOLLOWS:

1. The Assignor hereby assigns to the Assignee and the Assignee hereby accepts, on the terms and conditions set out in the written agreement for the sale and purchase of certain assets, contracts and intellectual property rights dated 7 May 2012, the full title to and ownership of all the intellectual property rights as listed in Schedule 1 (the Intellectual Property Rights).
2. In the event that the assignment is not or not fully effected or enforceable by this deed, each Party undertakes to execute, at the first request thereto by the other Party, any further deeds and documents that may be required to effect the assignment, including, but not limited to, the notification of the assignment to the relevant registers.
3. The Assignee will arrange for the registration of the assignment of the title to and ownership of the Intellectual Property Rights as soon as possible after it has been made and shall bear all costs of this assignment and registration.
4. The Assignor hereby grants full and irrevocable power of attorney to the Assignee, to submit this deed, together with the appropriate assignment/registration forms, to any appropriate register, authority or national or international competent intellectual and/or industrial property offices in any jurisdiction in which any of the Intellectual Property Rights are or can be registered.
5. This deed shall be governed by and construed in accordance with the laws of the Netherlands.
6. Any dispute arising from or connected with this deed is finally settled by arbitration in accordance with the rules of the Netherlands Arbitrage Institute (*Nederlands Arbitrage Instituut*). The arbitral tribunal will be composed of three arbitrators appointed in accordance with those rules. The place of arbitration will be Amsterdam, The Netherlands. The language of arbitration will be English. The arbitrators will decide according to the rules of law.

IN WITNESS WHEREOF the Parties have executed this deed in 2 original copies on 7 May 2012 in Amsterdam, the Netherlands:

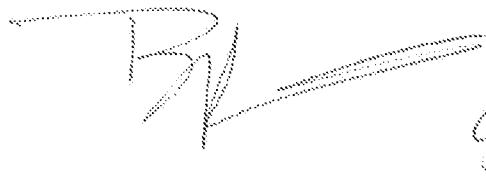
SIGNED by: Peter Smink  
For and on behalf of Helianthos B.V.  
the Assignor

4/5/2012



SIGNED by: Rombout Adriaan Swanborn  
For and on behalf of HyET ENERGY SYSTEMS B.V. i.o.  
the Assignee

3/5/2012



171	£10,000	1	O International patent	international patent: process for manufacturing a solar cell unit using a temporary substrate / barriers on solar cell, patent number : WO2006072355, exp. date 9-3-2022, countries (ultimo march 2012): BR*, AU, CN, IN, JP, KR, DE, FR, RU, AT, SE, DS, CH, CZ, DE, ES, FR, GB, IE, IT, NL, PT, RO, SI, SK, TR,* in application) the method of manufacturing a solar cell unit comprising the steps of: - providing an etchable conductive temporary substrate, - applying a layer of a transparent conductive oxide (TCO) onto the temporary substrate, - applying a Photoresist layer onto the TCO layer, - applying a back electrode layer, - applying a permanent carrier, - in any one of the preceding steps providing an etch resist on the temporary substrate in a pattern suitable to form a current collection grid after removal of the portion of the temporary substrate which is not covered with such resist, 2. Solar cell unit comprising a back electrode, a TCO layer and a current collection grid, where in the current collection grid - is a metallic current collection grid provided with a colored etch resist, or - has a cross-sectional depth, characterized by the ratio between the grid height and the grid width being at least 0.1, or - where in the grid is largest width at the interface of the TCO layer and that taper off to its smallest cross-section in a curved fashion, this process makes it possible to provide a solar cell unit comprising a highly conductive current collection grid by way of a simple process, if so desired the current collection grid may be provided with a color layer
172	£10,000	1	O International patent	international patent: method for making solar subcells / interconnection process, patent number : WO20080704879, exp. date 21/12/2027, countries (ultimo march 2012): countries TW*, EP*, HK*, JP*, KR*, CN*, CA*, MX*, IN*, DA, MY* (* in application) method for making a solar cell module comprising solar cells connected in series, comprising the steps of: 1. making in a system composed of a substrate overlaid by a first electrode layer, itself overlaid by an active layer, a first, interconnection groove, providing an interrupt in the front electrode and the active layer and a second, interconnection groove through the active layer, the first and the second grooves being positioned close to each other; 2. inserting an insulation compound into the interconnection grooves; 3. applying a lift-off compound onto the active layer at a position adjacent to the interconnection groove on the other side of the interconnection groove so that the insulation groove; 4. applying the second electrode; 5. removing the lift-off compound and the overlaying second electrode at that position to obtain a groove in the second electrode;
173	£10,000	1	O International patent	international patent: Photovoltaic module comprising layers with conductive paths / "B3 process", method to improve shadow tolerance of the PV module, patent number : WO2008132102 exp. date : 29/04/2018, countries (ultimo march 2012): countries IE*, JP, KR*, CN*, MX*, IN*, DA, EP*, TW* (* in application) 1. Photovoltaic module comprising a plurality of cells, each cell containing a substrate, a transparent conductive layer, a Photoresist layer, and a back electrode layer, where in the Photoresist layer comprises at least one pin or n/p silicon layer, characterized in that said silicon layer comprises 10 - 3000 conductive spots of recrystallized silicon per cm <sup>2</sup> , each having independently a surface of 10 - 2000 μm <sup>2</sup> ; 2. the methods for making the PV module [i] where to the p/n or np/n layer is locally heated at 100 - 3000 spots per cm <sup>2</sup> , each spot having independently a surface of 10 - 2500 μm <sup>2</sup> , where by the p/n or np/n silicon transformation of these spots to form conductive spots;
174	£50,000	1	O International patent	international patent: encapsulation system comprising two barrier layers, patent number : WO2009102734, exp. date : 18/07/2019, countries (ultimo march 2012): designated states TW*, AU*, CN*, EP*, IN*, JP*, KR*, MT*, US*, CA, TW* (* in application) 1. transparent encapsulation foil comprising a reinforcing layer and two barrier layers, where in the first barrier layer is positioned above the reinforcing layer and the second barrier layer is positioned below the reinforcing layer, where in the reinforcing layer comprises a fiber reinforced layer with fibers within average length of at least 2 cm, 2. process for manufacturing this transparent encapsulation foil [ii] 3. Solar cell system comprising this encapsulation [ii] (i) on the light receiving side of the solar cell 4. process for manufacturing the solar cell system comprising this encapsulation foil [ii]
175	£10,000	5	O International pending patent	international pending patent: patent number : WO2012060830, WO079, filing date 20/11/2009, countries (ultimo march 2012): designated states WO, a chemical vapour deposition process and reactor for applying a deposit layer on a substrate where in a heated support surface supports the substrate, while a flow of precursor gases is guided over the substrate through a gap between the support surface and an opposite guiding surface from a gas precursor inlet to an outlet, the inlet and the outlet are arranged at a different height, resulting in a non-uniform gass flow, the width of the substrate is at least 10 times the distance between the support surface and the guiding surface;
176	£10,000	5	O International patent	international patent: TCO with fused substrate and non-homogeneous film / process for manufacturing plies of a foil having an inorganic coating [e.g., TCO], patent number : WO2009126073, exp. date : 21/03/2026 countries (ultimo march 2012): countries TW*, CN*, EP*, KR, US*, JP* (* in application) process for manufacturing plies of a foil having an inorganic coating comprising the steps of: 1. providing an etchable temporary substrate foil 2. applying the inorganic coating onto the temporary substrate, 3. applying a permanent carrier, 4. optimally removing part of the temporary substrate at the cutting line, 5. cutting the foil along a cutting line, the pieces, where in the cutting line is positioned at the portion of the foil where the temporary substrate is removed in accordance with step 4, or where the temporary substrate is present and having a width of at least 1.25 mm relative to each side of the cutting line, 6. removing at least part of the temporary substrate;
177	£50,000	1	O International patent	international patent: connector housing assembly and method for housing a connector contact connecting a wire to a conducting path in a piece of foil / flexible place-able connector, with retentive force provided through protruding components, patent number : WO2008103304 exp. date : 24/09/2026, and 36/05/2026 countries (ultimo march 2012): countries IE, TW*, CN*, EP*, KR, US*, JP*, DA, PL, PT, US* (* in application) 1. connector housing assembly for accommodating a connector contact for use in connecting a wire to a conductor lead embedded in a piece of foil, at least one connector housing part comprising: a recess for accommodating at least part of the connector contact, an opening of the recess, at least one protruding component, adapted to insertion through the hole in the piece of foil, the connector housing assembly is configured to apply a retention force closing the face of the connector housing part provided with the recess opening towards the facing surface of the piece of foil to be exerted through at least one of the protruding components, 2. method for placing a connector in the hole of this connector housing;
178	£10,000	1	O International pending patent	international pending patent: connecting lead in a piece of foil / Connector housing/junction box, comprising a cable strain relief, patent number : WO2009103264, filing date 11/09/2009, countries (ultimo march 2012): countries IE, TW*, CN, connector housing for connecting an electric cable to a conductive lead, the connector housing comprising: a cable passage provided with an interior stop, a clamp ring fitting within the cable passage, the clamp ring being slideable over the cable and comprising a stop portion and one or more flexible tabs extending from the stop portion in radial directions, a locking ring provided with one or more retaining elements for engaging corresponding retaining elements in the cable passage to lock the locking ring in a locking position, where in the rim of the clamp ring are provided with an outwardly beveled pressure surface, the ring portion of the clamp ring abutting the interior stop in the cable passage, and where in the locking ring has one circumferential edge with an inwardly beveled pressure surface abutting the beveled pressure surface of the rim, where in the beveled pressure surface of the locking ring abuts the beveled ends of the clamp ring tabs radially inwardly when the locking ring is in the locking position, 2. Photovoltaic module provided with thin film solar sheet with fire retardant heat capacity;
179	£10,000	1	O International patent	international patent: hybrid roof covering element, patent number : WO2012060835, exp. date 9-8-2020, countries (ultimo march 2012): countries TW*, CN, JP, KR, US* (* in application) the invention pertains to a hybrid roof covering element suitable for simultaneously insulating a medium and generating electricity, the element comprises a flexible thin film solar cell sheet having a heat capacity of less than 3.5 J/m <sup>2</sup> K, preferable less than 200 J/m <sup>2</sup> K, the use of a thin film solar cell sheet having such a low heat capacity makes it possible to obtain a hybrid roof covering element with a high response speed. Note, the patent protection comprises any flexible thin film solar sheet with fire retardant heat capacity;
180	£10,000	5	O International pending patent	international pending patent: device for processing a foil substrate (PECVD, turning tool) EP application No. 05166592.0, filing date 27/7/2009, countries (ultimo march 2012): designated states EP, TW, CN, device for processing a foil substrate, e.g. in a roll-to-roll process, comprising: - a holder for a roll of the foil substrate, a transport unit for involving the roll of foil substrate and transporting it in a transport direction along the process, - at least one reflecting rollers with an axis of rotation which is parallel to the surface of the passing foil substrate and which is not under right angles with the transport direction, optionally the reflecting rollers comprise independently moveable axial segments and a driving means, such as a tracer pin mechanism, moving the segments to compensate for lateral movement by the foil substrate;

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